

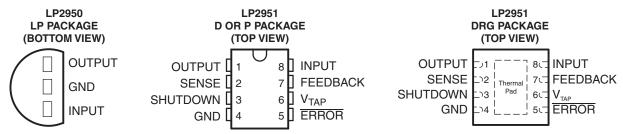
ADJUSTABLE MICROPOWER VOLTAGE REGULATORS WITH SHUTDOWN

Check for Samples: LP2950, LP2951

FEATURES

- Wide Input Range: Up to 30 V
- Rated Output Current of 100 mA
- Low Dropout: 380 mV (Typ) at 100 mA
- Low Quiescent Current: 75 μA (Typ)
- Tight Line Regulation: 0.03% (Typ)
- Tight Load Regulation: 0.04% (Typ)
- High V_O Accuracy
 - 1.4% at 25°C
 - 2% Over Temperature
- Can Be Used as a Regulator or Reference

- Stable With Low ESR (>12 mΩ) Capacitors
- Current- and Thermal-Limiting Features
- LP2950 Only (3-Pin Package)
 - Fixed-Output Voltages of 5 V, 3.3 V, and 3 V
- LP2951 Only (8-Pin Package)
 - Fixed- or Adjustable-Output Voltages:
 5 V/ADJ, 3.3 V/ADJ, and 3 V/ADJ
 - Low-Voltage Error Signal on Falling Output
 - Shutdown Capability
 - Remote Sense Capability for Optimal Output Regulation and Accuracy



DESCRIPTION/ORDERING INFORMATION

The LP2950 and LP2951 devices are bipolar, low-dropout voltage regulators that can accommodate a wide input supply-voltage range of up to 30 V. The easy-to-use, 3-pin LP2950 is available in fixed-output voltages of 5 V, 3.3 V, and 3 V. However, the 8-pin LP2951 is able to output either a fixed or adjustable output from the same device. By tying the OUTPUT and SENSE pins together, and the FEEDBACK and V_{TAP} pins together, the LP2951 outputs a fixed 5 V, 3.3 V, or 3 V (depending on the version). Alternatively, by leaving the SENSE and V_{TAP} pins open and connecting FEEDBACK to an external resistor divider, the output can be set to any value between 1.235 V to 30 V.

The 8-pin LP2951 also offers additional functionality that makes it particularly suitable for battery-powered applications. For example, a logic-compatible shutdown feature allows the regulator to be put in standby mode for power savings. In addition, there is a built-in supervisor reset function in which the ERROR output goes low when V_{OUT} drops by 6% of its nominal value for whatever reasons – due to a drop in V_{IN} , current limiting, or thermal shutdown.

The LP2950 and LP2951 are designed to minimize all error contributions to the output voltage. With a tight output tolerance (0.5% at 25°C), a very low output voltage temperature coefficient (20 ppm typical), extremely good line and load regulation (0.3% and 0.4% typical), and remote sensing capability, the parts can be used as either low-power voltage references or 100-mA regulators.



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.



ORDERING INFORMATION(1)

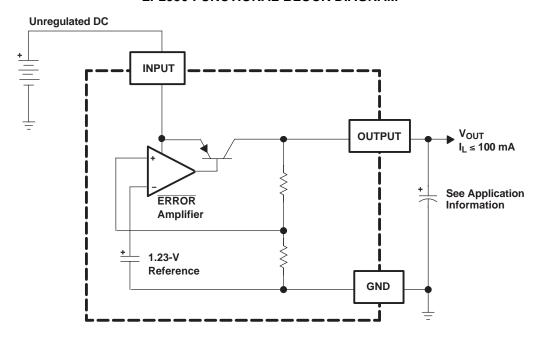
T _A	V _{OUT} (NOM)	PACKAG	BE ⁽²⁾	ORDERABLE PART NUMBER	TOP-SIDE MARKING
		TO 000/TO 00 . I D	Bulk of 1000	LP2950-30LP	14/45000
		TO-226/TO-92 – LP	Reel of 2000	LP2950-30LPR	KY5030
	3 V	PDIP – P	Tube of 50	LP2951-30P	PREVIEW
	3 V	SOIC - D	Tube of 75	LP2951-30D	KY5130
		201C – D	Reel of 2500	LP2951-30DR	- K15130
		WSON - DRG	Reel of 1000	LP2951-30DRGR	ZUD
		TO 226/TO 02 LD	Bulk of 1000	LP2950-33LP	LVE022
		TO-226/TO-92 – LP	Reel of 2000	LP2950-33LPR	
	3.3 V	PDIP – P	Tube of 50	LP2951-33P	TBD
		COIC D	Tube of 75	LP2951-33D	1005422
–40°C to 125°C		SOIC - D	Reel of 2500	LP2951-33DR	KY5133
-40°C to 125°C		WSON - DRG	Reel of 1000	LP2951-33DRGR	ZUE
		TO-226/TO-92 – LP	Bulk of 1000	LP2950-50LP	PREVIEW
		10-220/10-92 – LP	Reel of 2000	LP2950-50LPR	KY5050
	5 V	PDIP – P	Tube of 50	LP2951-50P	PREVIEW
	5 V	SOIC - D	Tube of 75	LP2951-50D	10/5450
		201C – D	Reel of 2500	LP2951-50DR	
		WSON - DRG	Reel of 1000	LP2951-50DRGR	ZUF
		PDIP – P	Tube of 50	LP2951P	PREVIEW
	ADI	COIC D	Tube of 75	LP2951D	I DOOE4
	ADJ	SOIC-D	Reel of 2500	LP2951DR	LP2951
		WSON - DRG	Reel of 1000	LP2951DRGR	PREVIEW

⁽¹⁾ For the most current package and ordering information, see the Package Option Addendum at the end of this document, or see the TI web site at www.ti.com.

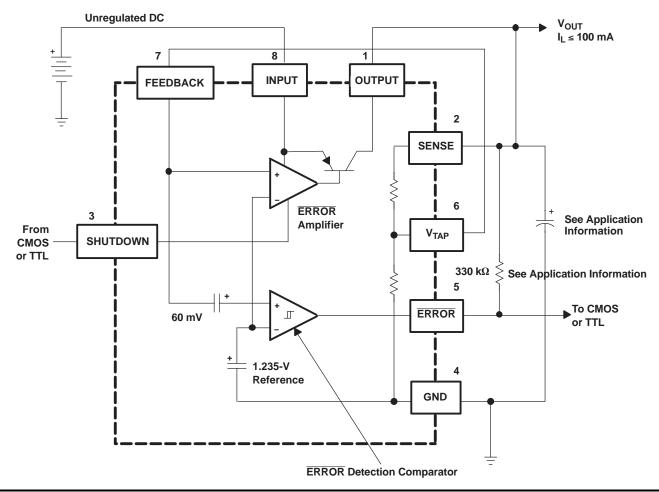
⁽²⁾ Package drawings, thermal data, and symbolization are available at www.ti.com/packaging.



LP2950 FUNCTIONAL BLOCK DIAGRAM



LP2951 FUNCTIONAL BLOCK DIAGRAM





ABSOLUTE MAXIMUM RATINGS(1)

over operating free-air temperature range (unless otherwise noted)

V_{IN}	Continuous input voltage range		-0.3 V to 30 V		
V_{SHDN}	SHUTDOWN input voltage range	–1.5 V to 30 V			
	ERROR comparator output voltage range (2)	–1.5 V to 30 V			
V_{FDBK}	FEEDBACK input voltage range (2) (3)	FEEDBACK input voltage range ⁽²⁾ (3)			
		D package ⁽⁵⁾	97°C/W		
	Declare the real importance (4)	DRG package (6)	52.44°C/W		
θ_{JA}	Package thermal impedance ⁽⁴⁾	LP package ⁽⁵⁾	140°C/W		
		P package ⁽⁵⁾	84.6°C/W		
T _J	Operating virtual-junction temperature		150°C		
T _{stg}	Storage temperature range	-65°C to 150°C			

⁽¹⁾ Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

May exceed input supply voltage

The package thermal impedance is calculated in accordance with JESD 51-7.

RECOMMENDED OPERATING CONDITIONS

		MIN	MAX	UNIT
V _{IN}	Supply input voltage	(1)	30	V
T_{J}	Operating virtual junction temperature	-40	125	°C

(1) Minimum V_{IN} is the greater of:

(a) 2 V (25°C), 2.3 V (over temperature), or

(b) V_{OUT(MAX)} + Dropout (Max) at rated I_L

If load is returned to a negative power supply, the output must be diode clamped to GND. Maximum power dissipation is a function of $T_J(max)$, θ_{JA} , and T_A . The maximum allowable power dissipation at any allowable ambient temperature is $P_D = (T_J(max) - T_A)/\theta_{JA}$. Operating at the absolute maximum T_J of 150°C can affect reliability.

The package thermal impedance is calculated in accordance with JESD 51-5.



ELECTRICAL CHARACTERISTICS

 $V_{IN} = V_{OUT} \text{ (nominal)} + 1 \text{ V, } I_L = 100 \text{ } \mu\text{A, } C_L = 1 \text{ } \mu\text{F (5-V versions)} \text{ or } C_L = 2.2 \text{ } \mu\text{F (3-V and 3.3-V versions)},$

8-pin version: FEEDBACK tied to V_{TAP} , OUTPUT tied to SENSE, $V_{SHUTDOWN} \le 0.7 \text{ V}$

	PARAMETER	TEST CONDITIONS	TJ	MIN	TYP	MAX	UNIT	
3-V VERSION	ON (LP295x-30)							
.,	O	1 100 1	25°C	2.970	3	3.030	.,	
V_{OUT}	Output voltage	I _L = 100 μA	-40°C to 125°C	2.940	3	3.060	V	
3.3-V VERS	SION (LP295x-33)		1					
\ /	Outracticality	1. 400	25°C	3.267	3.3	3.333		
V _{OUT}	Output voltage	I _L = 100 μA	-40°C to 125°C	3.234	3.3	3.366	V	
5-V VERSION	ON (LP295x-50)			·				
V	Output valtage	1 100	25°C	4.950	5	5.050	V	
V_{OUT}	Output voltage	I _L = 100 μA	-40°C to 125°C	4.900	5	5.100	V	
ALL VOLTA	AGE OPTIONS			·				
	Output voltage temperature coefficient (1)	Ι _L = 100 μΑ	-40°C to 125°C		20	100	ppm/°C	
	1 (2)	V 5/ 4 20 V	25°C	•	0.03	0.2	0/ 0/	
	Line regulation (2)	$V_{IN} = [V_{OUT(NOM)} + 1 V] \text{ to } 30 V$	-40°C to 125°C	•		0.4	%/V	
	(2)		25°C	•	0.04	0.2	0.4	
	Load regulation ⁽²⁾	$I_L = 100 \mu A \text{ to } 100 \text{ mA}$	-40°C to 125°C	•		0.3	- %	
			25°C		50	80		
., .,	D (3)	I _L = 100 μA	-40°C to 125°C	•		150	mV	
$V_{IN} - V_{OUT}$	Dropout voltage (3)	L 400 mA	25°C	•	380	450		
		I _L = 100 mA	-40°C to 125°C			600	1	
			25°C		75	120		
	OND	I _L = 100 μA	-40°C to 125°C	·		140	μA	
I _{GND}	GND current	1 400 1	25°C		8	12	0	
		$I_L = 100 \text{ mA}$	-40°C to 125°C			14	mA	
	Description of succession	$V_{IN} = V_{OUT(NOM)} - 0.5 V,$	25°C	·	110	170		
	Dropout ground current	I _L = 100 μA	-40°C to 125°C	·		200	μA	
	Ourman t Park		25°C	·	160	200	^	
	Current limit	V _{OUT} = 0 V	-40°C to 125°C	·		220	mA	
	Thermal regulation ⁽⁴⁾	I _L = 100 μA	25°C		0.05	0.2	%/W	
		C _L = 1 μF (5 V only)			430			
	Output noise (RMS),	C _L = 200 μF			160			
	10 Hz to 100 kHz	LP2951-50: C_L = 3.3 μ F, C_{Bypass} = 0.01 μ F between pins 1 and 7	25°C		100		μV	

⁽¹⁾ Output or reference voltage temperature coefficient is defined as the worst-case voltage change divided by the total temperature range.

⁽²⁾ Regulation is measured at constant junction temperature, using pulse testing with a low duty cycle. Changes in output voltage due to heating effects are covered under the specification for thermal regulation.

⁽³⁾ Dropout voltage is defined as the input-to-output differential at which the output voltage drops 100 mV, below the value measured at 1-V differential. The minimum input supply voltage of 2 V (2.3 V over temperature) must be observed.

⁽⁴⁾ Thermal regulation is defined as the change in output voltage at a time (T) after a change in power dissipation is applied, excluding load or line regulation effects. Specifications are for a 50-mA load pulse at V_{IN} = 30 V, V_{OUT} = 5 V (1.25-W pulse) for t = 10 ms.



 V_{IN} = V_{OUT} (nominal) + 1 V, I_L = 100 μ A, C_L = 1 μ F (5-V versions) or C_L = 2.2 μ F (3-V and 3.3-V versions), 8-pin version: FEEDBACK tied to V_{TAP} , OUTPUT tied to SENSE, $V_{SHUTDOWN}$ ≤ 0.7 V

PARAMETER	TEST CONDITIONS	TJ	MIN	TYP	MAX	UNIT	
(LP2951-xx) 8-PIN VERSION ONLY AD	J	1					
		25°C	1.218	1.235	1.252		
		-40°C to 125°C	1.212		1.257		
Reference voltage	$V_{OUT} = V_{REF}$ to $(V_{IN} - 1 \ V)$, $V_{IN} = 2.3 \ V$ to 30 V, $I_L = 100 \ \mu A$ to 100 mA	-40°C to 125°C	1.200		1.272	V	
Reference voltage temperature coefficient (5)		25°C		20		ppm/°C	
FFFDDA OK kita a susua st		25°C	·	20	40		
FEEDBACK bias current		-40°C to 125°C			60	nA	
FEEDBACK bias current temperature coefficient		25°C		0.1		nA/°C	
ERROR COMPARATOR			·				
Outrout le alse de auront	V 20 V	25°C		0.01	1		
Output leakage current	V _{OUT} = 30 V	-40°C to 125°C	·		2	μA	
Outract laws alto as	$V_{IN} = V_{OUT(NOM)} - 0.5 V,$	25°C	·	150	250	>/	
Output low voltage	$I_{OL} = 400 \mu\text{A}$	-40°C to 125°C			400	mV	
Upper threshold voltage		25°C	40	60		\/	
(ERROR output high) ⁽⁶⁾		-40°C to 125°C	25			mV	
Lower threshold voltage		25°C		75	95	.,	
(ERROR output low) (6)		-40°C to 125°C			140	0 mV	
Hysteresis ⁽⁶⁾		25°C		15		mV	
SHUTDOWN INPUT		1					
land to stand to sell and	Low (regulator ON)	4000 1- 40500			0.7		
Input logic voltage	High (regulator OFF)	-40°C to 125°C	2			V	
	V 0.4V	25°C	·	30	50		
OLULTDOWAL control	$V_{TAP} = 2.4 \text{ V}$	-40°C to 125°C			100	μΑ	
SHUTDOWN input current	V 00 V	25°C		450	600		
	$V_{TAP} = 30 \text{ V}$	-40°C to 125°C	·		750		
Regulator output current	V _{SHUTDOWN} ≥ 2 V,	25°C		3	10		
in shutdown	$V_{IN} \le 30 \text{ V}, V_{OUT} = 0,$ FEEDBACK tied to V_{TAP}	-40°C to 125°C			20	μA	

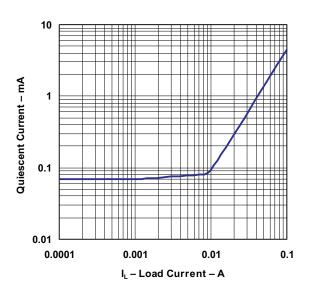
⁽⁵⁾ Output or reference voltage temperature coefficient is defined as the worst-case voltage change divided by the total temperature range.

Comparator thresholds are expressed in terms of a voltage differential equal to the nominal reference voltage (measured at $V_{IN} - V_{OUT} = 1 \text{ V}$) minus FEEDBACK terminal voltage. To express these thresholds in terms of output voltage change, multiply by the error amplifier gain = V_{OUT}/V_{REF} = (R1 + R2)/R2. For example, at a programmed output voltage of 5 V, the ERROR output is specified to go low when the output drops by 95 mV × 5 V/1.235 V = 384 mV. Thresholds remain constant as a percentage of V_{OUT} (as V_{OUT} is varied), with the low-output warning occurring at 6% below nominal (typ) and 7.7% (max).

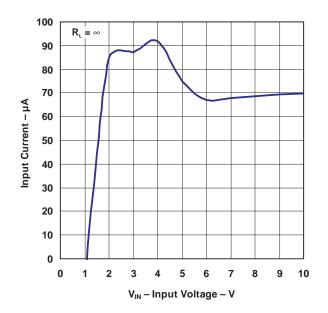


TYPICAL CHARACTERISTICS

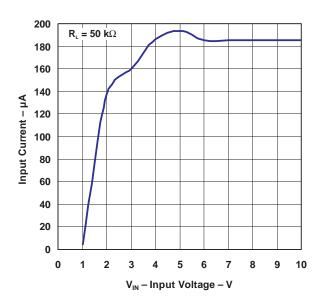
QUIESCENT CURRENT vs LOAD CURRENT



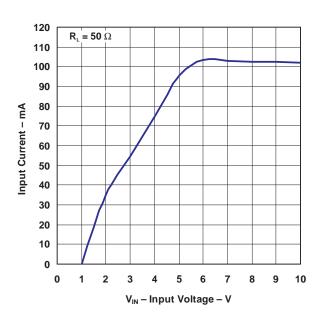
INPUT CURRENT vs INPUT VOLTAGE



INPUT CURRENT vs INPUT VOLTAGE

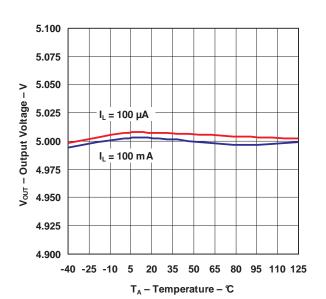


INPUT CURRENT vs
INPUT VOLTAGE

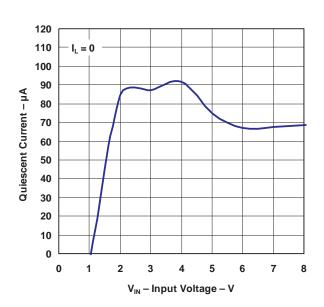




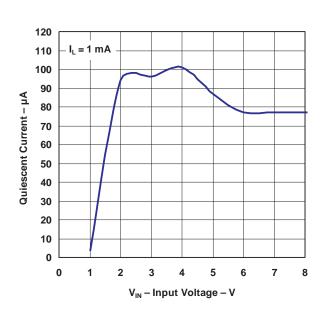
OUTPUT VOLTAGE vs TEMPERATURE



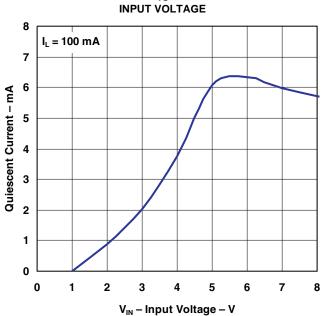
QUIESCENT CURRENT vs INPUT VOLTAGE



QUIESCENT CURRENT vs INPUT VOLTAGE

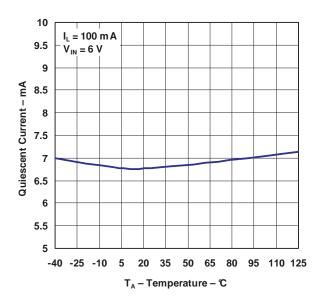


QUIESCENT CURRENT vs

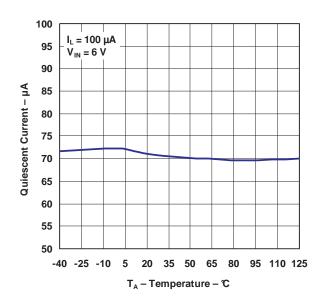




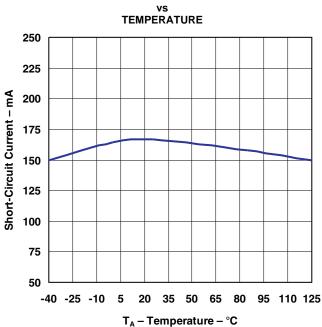
QUIESCENT CURRENT vs TEMPERATURE



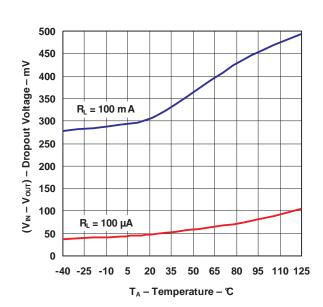
QUIESCENT CURRENT vs TEMPERATURE



SHORT-CIRCUIT CURRENT

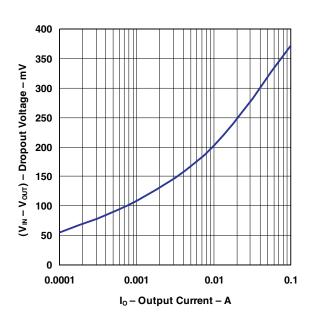


DROPOUT VOLTAGE vs TEMPERATURE

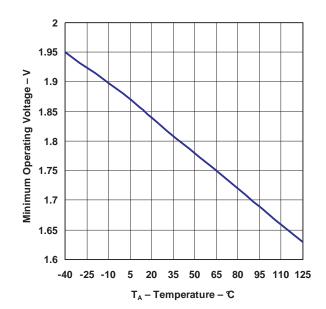




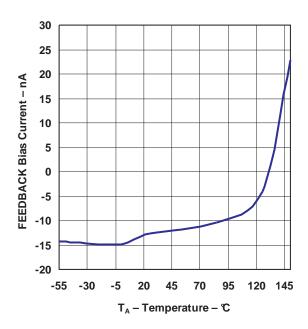
DROPOUT VOLTAGE vs OUTPUT CURRENT



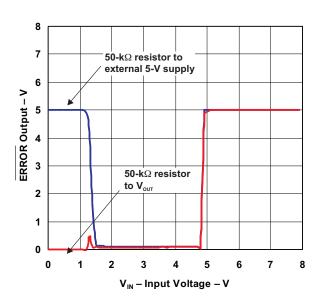
LP2951 MINIMUM OPERATING VOLTAGE vs TEMPERATURE



LP2951 FEEDBACK BIAS CURRENT vs TEMPERATURE

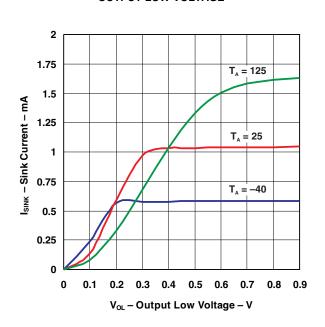


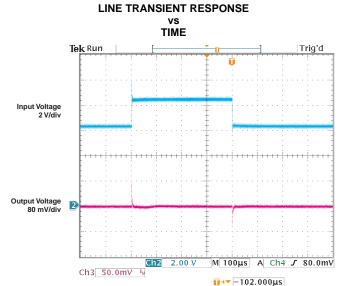
LP2951 ERROR COMPARATOR OUTPUT vs INPUT VOLTAGE



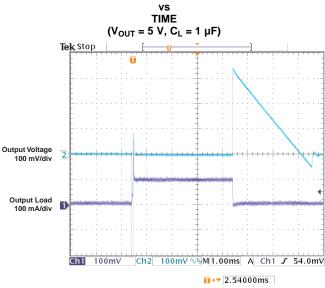


LP2951 ERROR COMPARATOR SINK CURRENT vs OUTPUT LOW VOLTAGE

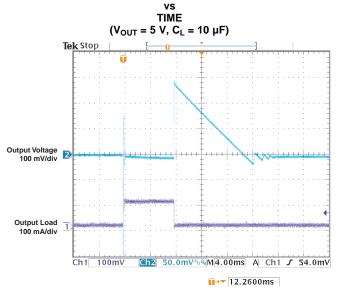




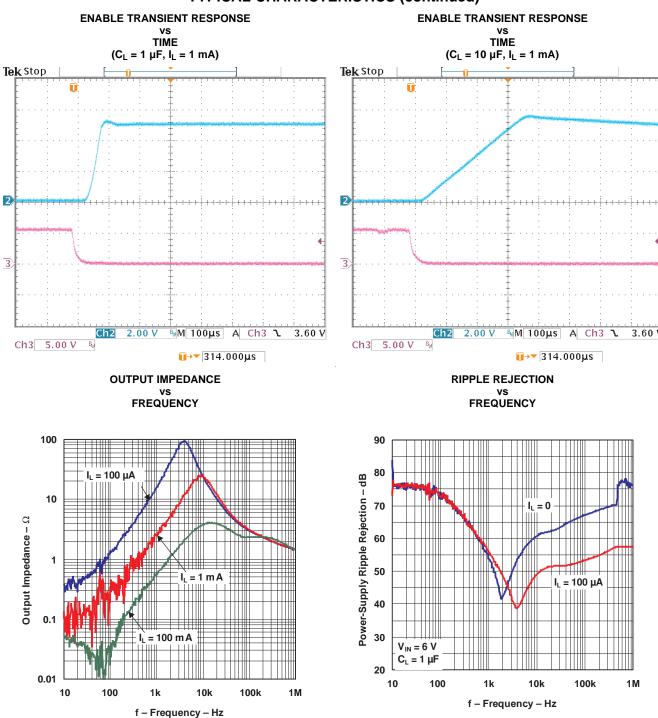
LOAD TRANSIENT RESPONSE



LOAD TRANSIENT RESPONSE

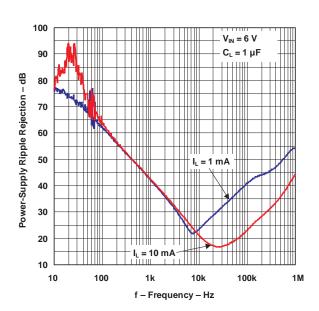




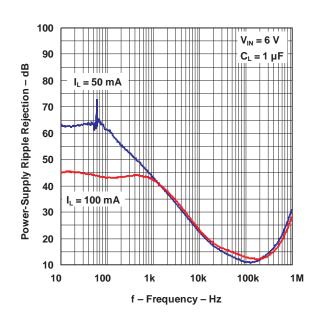




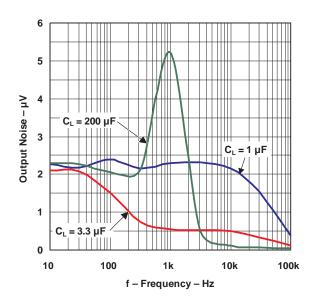
RIPPLE REJECTION vs FREQUENCY



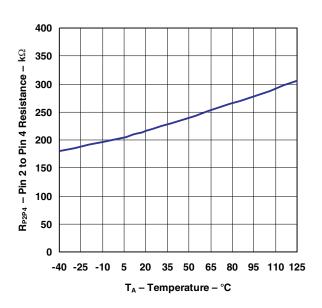
RIPPLE REJECTION vs FREQUENCY



LP2951 OUTPUT NOISE vs FREQUENCY



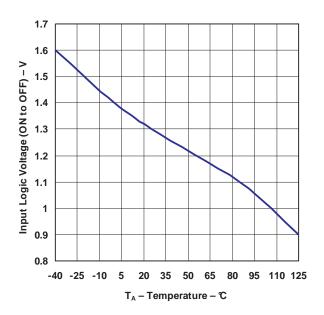
LP2951 DIVIDER RESISTANCE vs TEMPERATURE



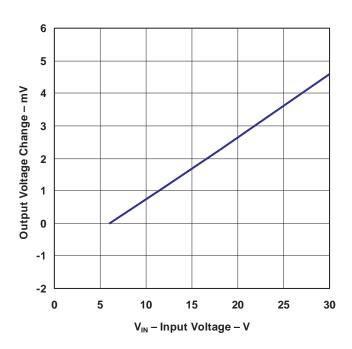


SHUTDOWN THRESHOLD VOLTAGE (OFF TO ON) vs TEMPERATURE

SHUTDOWN THRESHOLD VOLTAGE (ON TO OFF) vs TEMPERATURE



LINE REGULATION vs INPUT VOLTAGE





APPLICATION INFORMATION

Input Capacitor (C_{IN})

A 1-μF (tantalum, ceramic, or aluminum) electrolytic capacitor should be placed locally at the input of the LP2950 or LP2951 if there is, or will be, significant impedance between the ac filter capacitor and the input; for example, if a battery is used as the input or if the ac filter capacitor is located more than 10 in away. There are no ESR requirements for this capacitor, and the capacitance can be increased without limit.

Output Capacitor (Cout)

As with most PNP LDOs, stability conditions require the output capacitor to have a minimum capacitance and an ESR that falls within a certain range.

Capacitance Value

For $V_{OUT} \ge 5$ V, a minimum of 1 μF is required. For lower V_{OUT} , the regulator's loop gain is running closer to unity gain and, thus, has lower phase margins. Consequently, a larger capacitance is needed for stability. For $V_{OUT} = 3$ V or 3.3 V, a minimum of 2.2 μF is recommended. For worst case, $V_{OUT} = 1.23$ V (using the ADJ version), a minimum of 3.3 μF is recommended. C_{OUT} can be increased without limit and only improves the regulator stability and transient response. Regardless of its value, the output capacitor should have a resonant frequency less than 500 kHz.

The minimum capacitance values given above are for maximum load current of 100 mA. If the maximum expected load current is less than 100 mA, then lower values of C_{OUT} can be used. For instance, if I_{OUT} < 10 mA, then only 0.33 μ F is required for C_{OUT} . For I_{OUT} < 1 mA, 0.1 μ F is sufficient for stability requirements. Thus, for a worst-case condition of 100-mA load and V_{OUT} = V_{REF} = 1.235 V (representing the highest load current and lowest loop gain), a minimum C_{OUT} of 3.3 μ F is recommended.

For the LP2950, no load stability is inherent in the design — a desirable feature in CMOS circuits that are put in standby (such as RAM keep-alive applications). If the LP2951 is used with external resistors to set the output voltage, a minimum load current of 1 μ A is recommended through the resistor divider.

ESR Range

The regulator control loop relies on the ESR of the output capacitor to provide a zero to add sufficient phase margin to ensure unconditional regulator stability; this requires the closed-loop gain to intersect the open-loop response in a region where the open-loop gain rolls off at 20 dB/decade. This ensures that the phase always is less than 180° (phase margin greater than 0°) at unity gain. Thus, a minimum-maximum range for the ESR must be observed.

The upper limit of this ESR range is established by the fact that too high an ESR could result in the zero occurring too soon, causing the gain to roll off too slowly, which, in turn allows a third pole to appear before unity gain and introduce enough phase shift to cause instability. This typically limits the max ESR to approximately Ω .

Conversely, the lower limit of the ESR is tied to the fact that too low an ESR shifts the zero too far out (past unity gain) and, thus, allows the gain to roll off at 40 dB/decade at unity gain, with a resulting phase shift of greater than 180°. Typically, this limits the minimum ESR to approximately 20 m Ω to 30 m Ω .

For specific ESR requirements, see Typical Characteristics.



Capacitor Types

Most tantalum or aluminum electrolytics are suitable for use at the input. Film-type capacitors also work, but at higher cost. When operating at low temperature, care should be taken with aluminum electrolytics, as their electrolytes often freeze at -30°C. For this reason, solid tantalum capacitors should be used at temperatures below -25°C.

Ceramic capacitors can be used, but due to their low ESR (as low as 5 m Ω to 10 m Ω), they may not meet the minimum ESR requirement previously discussed. If a ceramic capacitor is used, a series resistor between 0.1 Ω to 2 Ω must be added to meet the minimum ESR requirement. In addition, ceramic capacitors have one glaring disadvantage that must be taken into account — a poor temperature coefficient, where the capacitance can vary significantly with temperature. For instance, a large-value ceramic capacitor (\geq 2.2 μ F) can lose more than half of its capacitance as temperature rises from 25°C to 85°C. Thus, a 2.2- μ F capacitor at 25°C drops well below the minimum C_{OUT} required for stability as ambient temperature rises. For this reason, select an output capacitor that maintains the minimum 2.2 μ F required for stability for the entire operating temperature range.

C_{BYPASS}: Noise and Stability Improvement

In the LP2951, an external FEEDBACK pin directly connected to the error amplifier noninverting input can allow stray capacitance to cause instability by shunting the error amplifier feedback to GND, especially at high frequencies. This is worsened if high-value external resistors are used to set the output voltage, because a high resistance allows the stray capacitance to play a more significant role; i.e., a larger RC time delay is introduced between the output of the error amplifier and its FEEDBACK input, leading to more phase shift and lower phase margin. A solution is to add a 100-pF bypass capacitor (C_{BYPASS}) between OUTPUT and FEEDBACK; because C_{BYPASS} is in parallel with R1, it lowers the impedance seen at FEEDBACK at high frequencies, in effect offsetting the effect of the parasitic capacitance by providing more feedback at higher frequencies. More feedback forces the error amplifier to work at a lower loop gain, so C_{OUT} should be increased to a minimum of 3.3 µF to improve the regulator's phase margin.

 C_{BYPASS} can be also used to reduce output noise in the LP2951. This bypass capacitor reduces the closed loop gain of the error amplifier at the high frequency, so noise no longer scales with the output voltage. This improvement is more noticeable with higher output voltages, because loop gain reduction is greatest. A suitable C_{BYPASS} is calculated as shown in Equation 1:

$$f_{(CBYPASS)} \simeq 200 \text{ Hz} \rightarrow C_{BYPASS} = \frac{1}{2\pi \times R1 \times 200 \text{ Hz}}$$
 (1)

On the 3-pin LP2950, noise reduction can be achieved by increasing the output capacitor, which causes the regulator bandwidth to be reduced, therefore, eliminating high-frequency noise. However, this method is relatively inefficient, as increasing C_{OUT} from 1 μF to 220 μF only reduces the regulator's output noise from 430 μV to 160 μV (over a 100-kHz bandwidth).

ERROR Function (LP2951 Only)

The LP2951 has a low-voltage detection comparator that outputs a logic low when the output voltage drops by 6% from its nominal value, and outputs a logic high when V_{OUT} has reached 95% of its nominal value. This 95% of nominal figure is obtained by dividing the built-in offset of 60 mV by the 1.235-V bandgap reference, and remains independent of the programmed output voltage. For example, the trip-point threshold (ERROR output goes high) typically is 4.75 V for a 5-V output and 11.4 V for a 12-V output. Typically, there is a hysteresis of 15 mV between the thresholds for high and low ERROR output.

A timing diagram is shown in Figure 1 for \overline{ERROR} vs V_{OUT} (5 V), as V_{IN} is \underline{ramped} up and down. \overline{ERROR} becomes valid (low) when V_{IN} 1.3 V. When V_{IN} 5 V, V_{OUT} = 4.75 V, causing \overline{ERROR} to go high. Because the dropout voltage is load dependent, the output trip-point threshold is reached at different values of V_{IN} , depending on the load current. For instance, at higher load current, \overline{ERROR} goes high at a slightly higher value of V_{IN} , and vice versa for lower load current. The output-voltage trip point remains at 4.75 V, regardless of the load. Note that when $V_{IN} \le 1.3$ V, the \overline{ERROR} comparator output is turned off and pulled high to its pullup voltage. If V_{OUT} is used as the pullup voltage, rather than an external 5-V source, \overline{ERROR} typically is 1.2 V. In this condition, an equal resistor divider (10 k Ω is suitable) can be tied to \overline{ERROR} to divide down the voltage to a valid logic low during any fault condition, while still enabling a logic high during normal operation.



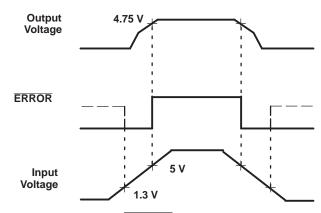


Figure 1. ERROR Output Timing

Because the $\overline{\text{ERROR}}$ comparator has an open-collector output, an external pullup resistor is required to pull the output up to V_{OUT} or another supply voltage (up to 30 V). The output of the comparator is rated to sink up to 400 μA . A suitable range of values for the pullup resistor is from 100 $k\Omega$ to 1 $M\Omega$. If $\overline{\text{ERROR}}$ is not used, it can be left open.

Programming Output Voltage (LP2951 Only)

A unique feature of the LP2951 is its ability to output either a fixed voltage or an adjustable voltage, depending on the external pin connections. To output the internally programmed fixed voltage, tie the SENSE pin to the OUTPUT pin and the FEEDBACK pin to the V_{TAP} pin. Alternatively, a user-programmable voltage ranging from the internal 1.235-V reference to a 30-V max can be set by using an external resistor divider pair. The resistor divider is tied to V_{OUT} , and the divided-down voltage is tied directly to FEEDBACK for comparison against the internal 1.235-V reference. To satisfy the steady-state condition in which its two inputs are equal, the error amplifier drives the output to equal Equation 2:

$$V_{OUT} = V_{REF} \times \left(1 + \frac{R1}{R2}\right) - I_{FB}R_1$$

Where:

V_{REF} = 1.235 V applied across R2

I_{FB} = FEEDBACK bias current, typically 20 nA

A minimum regulator output current of 1 μ A must be maintained. Thus, in an application where a no-load condition is expected (for example, CMOS circuits in standby), this 1- μ A minimum current must be provided by the resistor pair, effectively imposing a maximum value of R2 = 1.2 M Ω (1.235 V/1.2 M Ω 1 μ A).

 I_{FB} = 20 nA introduces an error of 0.02% in V_{OUT} . This can be offset by trimming R1. Alternatively, increasing the divider current makes I_{FB} less significant, thus, reducing its error contribution. For instance, using R2 = 100 k Ω reduces the error contribution of I_{FB} to 0.17% by increasing the divider current to 12 μ A. This increase in the divider current still is small compared to the 600- μ A typical quiescent current of the LP2951 under no load. (2)



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PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
LP2950-30LP	ACTIVE	TO-92	LP	3	1000	Pb-Free (RoHS)	CU SN	N / A for Pkg Type
LP2950-30LPE3	ACTIVE	TO-92	LP	3	1000	Pb-Free (RoHS)	CU SN	N / A for Pkg Type
LP2950-30LPR	ACTIVE	TO-92	LP	3	2000	Pb-Free (RoHS)	CU SN	N / A for Pkg Type
LP2950-30LPRE3	ACTIVE	TO-92	LP	3	2000	Pb-Free (RoHS)	CU SN	N / A for Pkg Type
LP2950-33LPE3	ACTIVE	TO-92	LP	3	1000	Pb-Free (RoHS)	CU SN	N / A for Pkg Type
LP2950-33LPRE3	ACTIVE	TO-92	LP	3	2000	Pb-Free (RoHS)	CU SN	N / A for Pkg Type
LP2950-50LPRE3	ACTIVE	TO-92	LP	3	2000	Pb-Free (RoHS)	CU SN	N / A for Pkg Type
LP2951-30D	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
LP2951-30DG4	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
LP2951-30DR	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
LP2951-30DRG4	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
LP2951-30DRGR	ACTIVE	SON	DRG	8	1000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR
LP2951-33D	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
LP2951-33DG4	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
LP2951-33DR	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
LP2951-33DRG4	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
LP2951-33DRGR	ACTIVE	SON	DRG	8	1000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR
LP2951-50D	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
LP2951-50DG4	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
LP2951-50DR	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
LP2951-50DRG4	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
LP2951-50DRGR	ACTIVE	SON	DRG	8	1000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR
LP2951D	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
LP2951DG4	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
LP2951DR	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM



PACKAGE OPTION ADDENDUM

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Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins Pa	ackage Qty	Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
LP2951DRG4	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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TAPE AND REEL INFORMATION





		Dimension designed to accommodate the component width
		Dimension designed to accommodate the component length
	K0	Dimension designed to accommodate the component thickness
		Overall width of the carrier tape
Γ	P1	Pitch between successive cavity centers

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
LP2951-30DR	SOIC	D	8	2500	330.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1
LP2951-33DR	SOIC	D	8	2500	330.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1
LP2951-50DR	SOIC	D	8	2500	330.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1
LP2951DR	SOIC	D	8	2500	330.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1



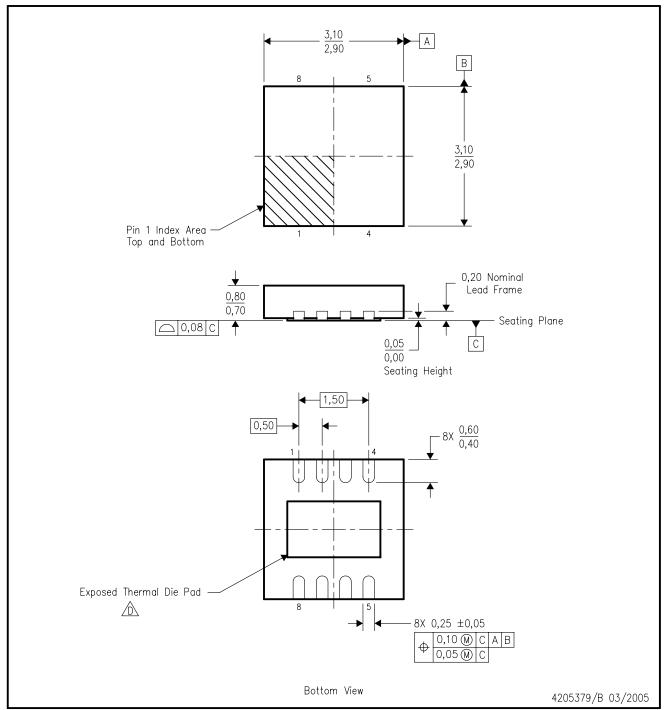


*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
LP2951-30DR	SOIC	D	8	2500	340.5	338.1	20.6
LP2951-33DR	SOIC	D	8	2500	340.5	338.1	20.6
LP2951-50DR	SOIC	D	8	2500	340.5	338.1	20.6
LP2951DR	SOIC	D	8	2500	340.5	338.1	20.6

DRG (S-PDSO-N8)

PLASTIC SMALL OUTLINE



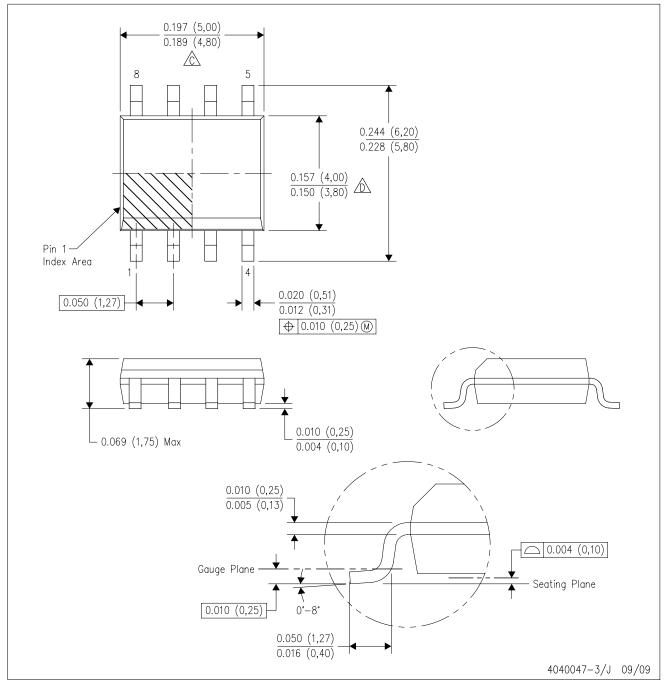
- All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M-1994. NOTES:

 - B. This drawing is subject to change without notice.C. SON (Small Outline No-Lead) package configuration.
 - The package thermal pad must be soldered to the board for thermal and mechanical performance. See the Product Data Sheet for details regarding the exposed thermal pad dimensions.
 - E. JEDEC MO-229 package registration pending.



D (R-PDSO-G8)

PLASTIC SMALL-OUTLINE PACKAGE



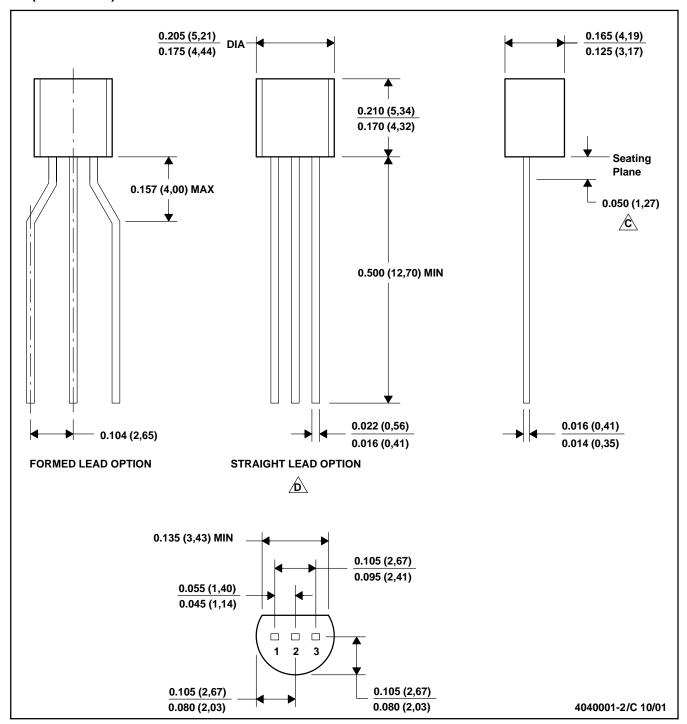
NOTES:

- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed .006 (0,15) per end.
- Body width does not include interlead flash. Interlead flash shall not exceed .017 (0,43) per side.
- E. Reference JEDEC MS-012 variation AA.



LP (O-PBCY-W3)

PLASTIC CYLINDRICAL PACKAGE



NOTES: A. All linear dimensions are in inches (millimeters).

B. This drawing is subject to change without notice.

C.\ Lead dimensions are not controlled within this area

√D.\ FAlls within JEDEC TO -226 Variation AA (TO-226 replaces TO-92)

E. Shipping Method:

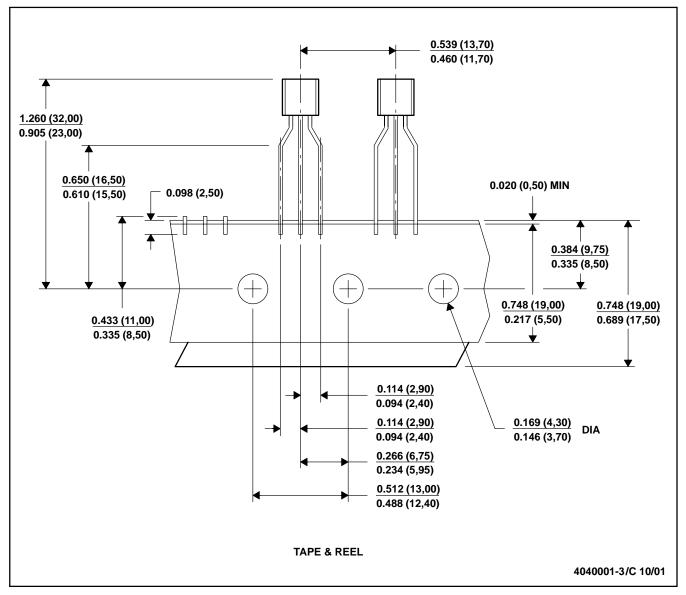
Straight lead option available in bulk pack only.

Formed lead option available in tape & reel or ammo pack.



LP (O-PBCY-W3)

PLASTIC CYLINDRICAL PACKAGE



NOTES: A. All linear dimensions are in inches (millimeters).

B. This drawing is subject to change without notice.

C. Tape and Reel information for the Format Lead Option package.

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